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Sohn et al.

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(54) **SEMICONDUCTOR DEVICE**

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(**) Term: **14 Years**

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(30) **Foreign Application Priority Data**

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(51) **LOC (10) Cl.** **13-03**

(52) **U.S. Cl.**
USPC **D13/182**

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USPC D13/110, 182, 184, 713, 728, 736, 760,
D13/761, 775, 679.01, 820, 361, 666, 668,
D13/678, 684, 690, 257, 71.5, 252, 324,
D13/250, 253, 174, 64, 65, 66, 438
See application file for complete search history.

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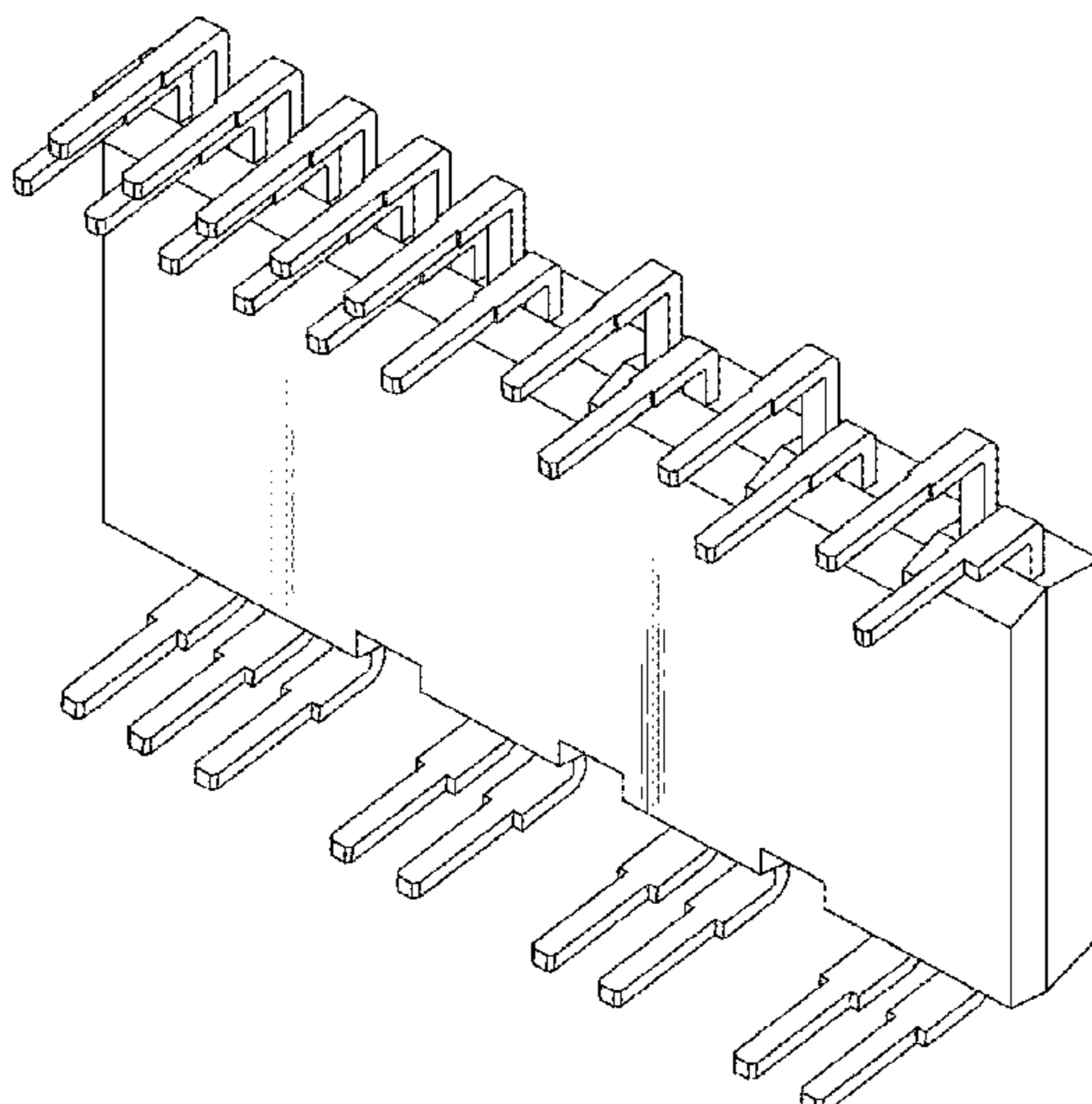
(57) **CLAIM**

The ornamental design for a semiconductor device, as shown and described.

DESCRIPTION

FIG. 1 is a perspective view of a semiconductor device showing our new design;
FIG. 2 is a front view thereof;
FIG. 3 is a rear view thereof;
FIG. 4 is a left side view thereof,
FIG. 5 is a right side view thereof;
FIG. 6 is a top plan view thereof; and,
FIG. 7 is a bottom plan view thereof.

1 Claim, 7 Drawing Sheets



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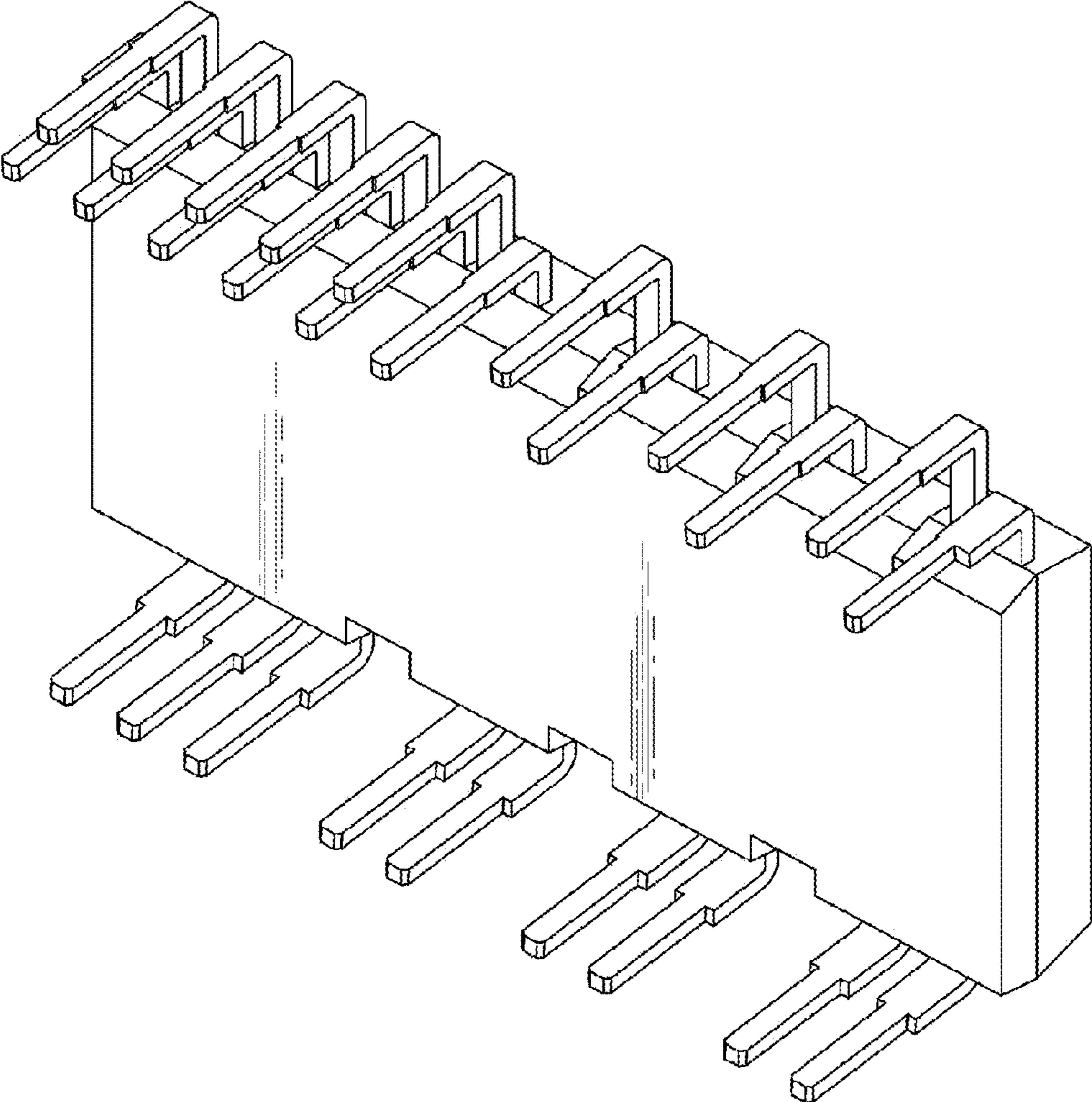


FIG. 1

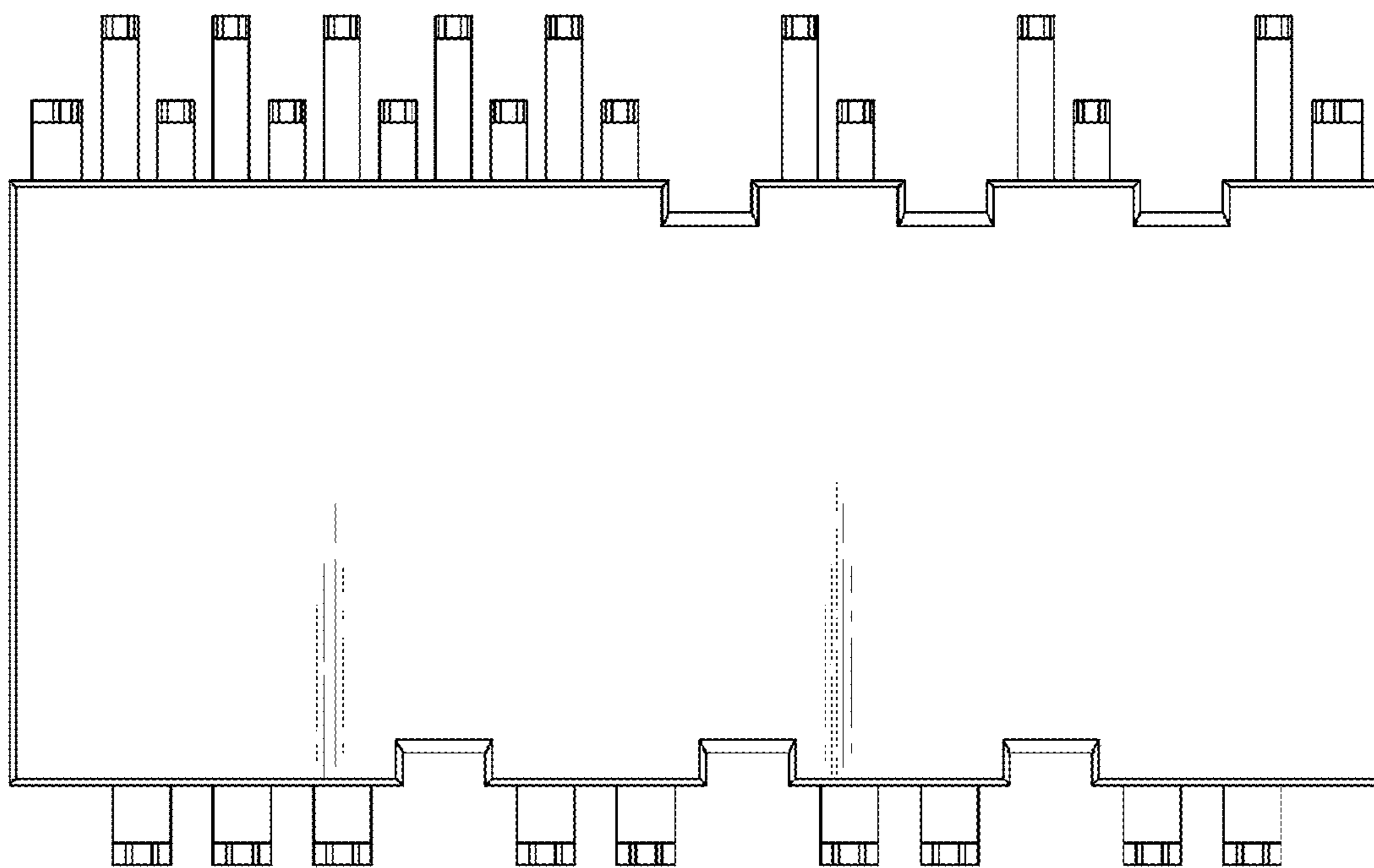


FIG. 2

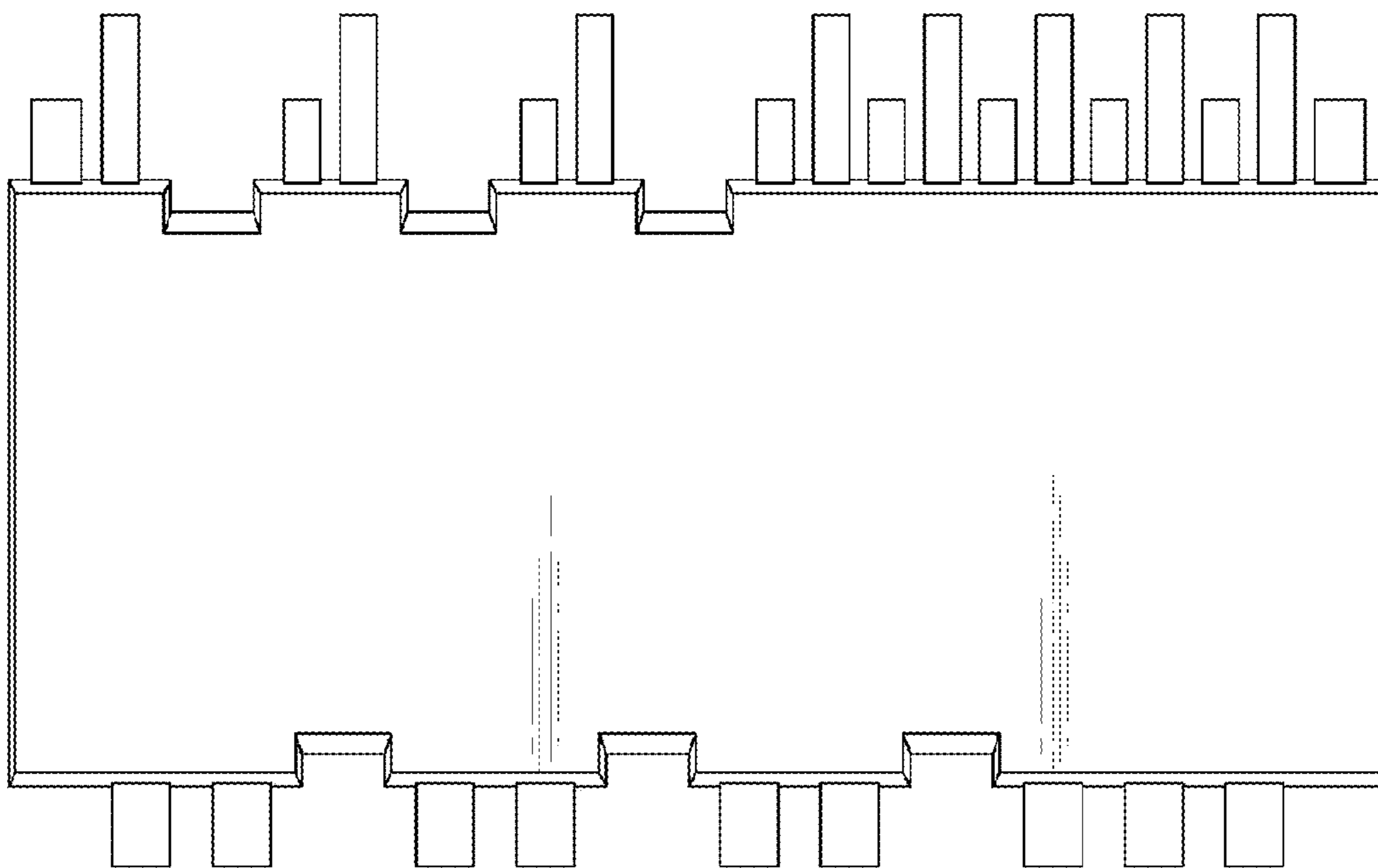


FIG. 3

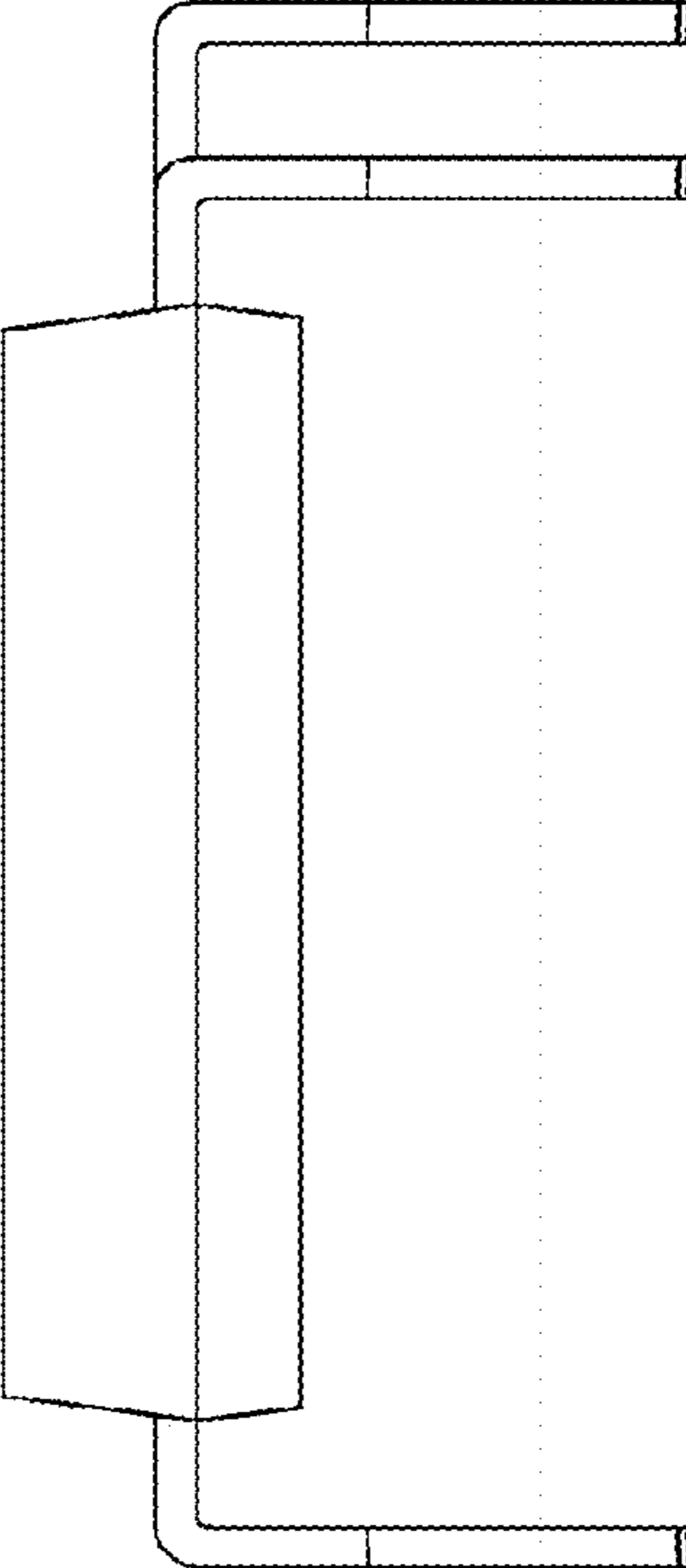


FIG. 4

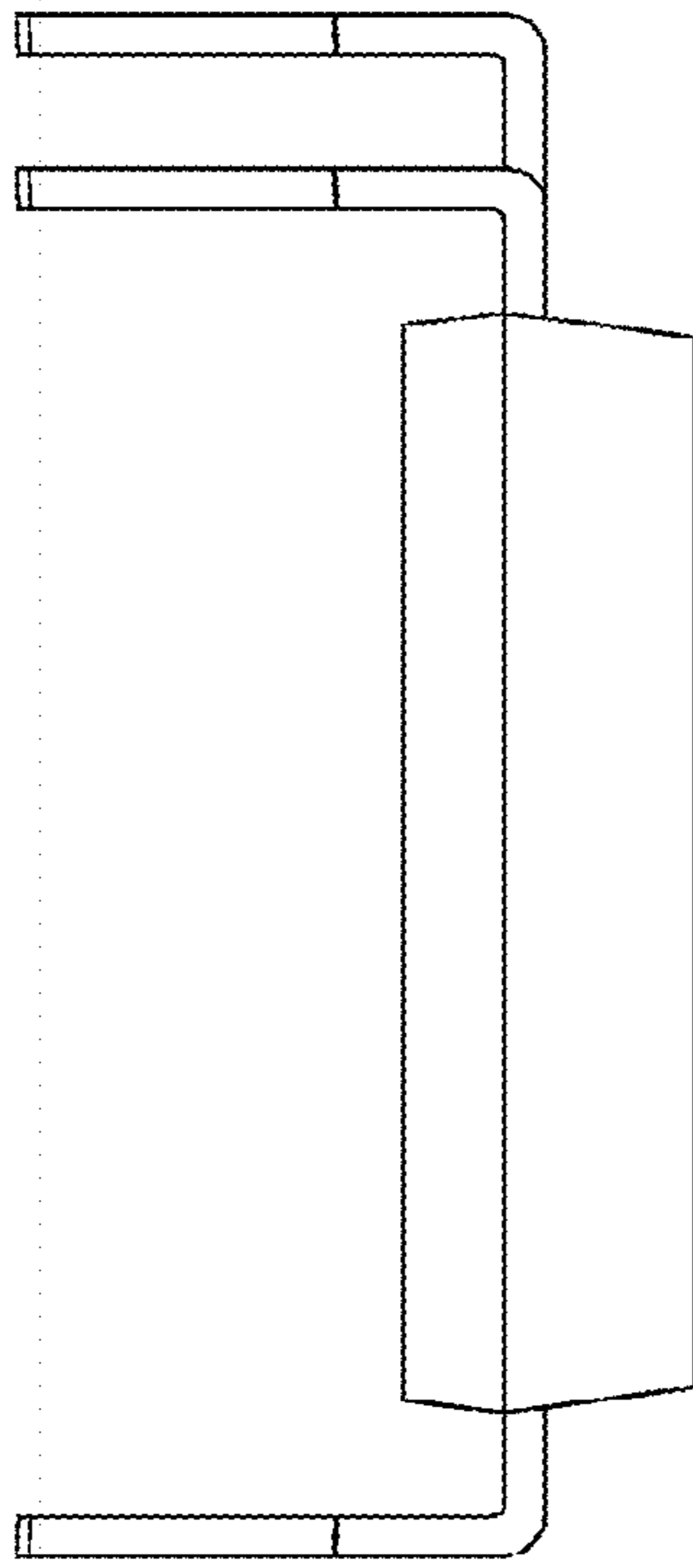


FIG. 5

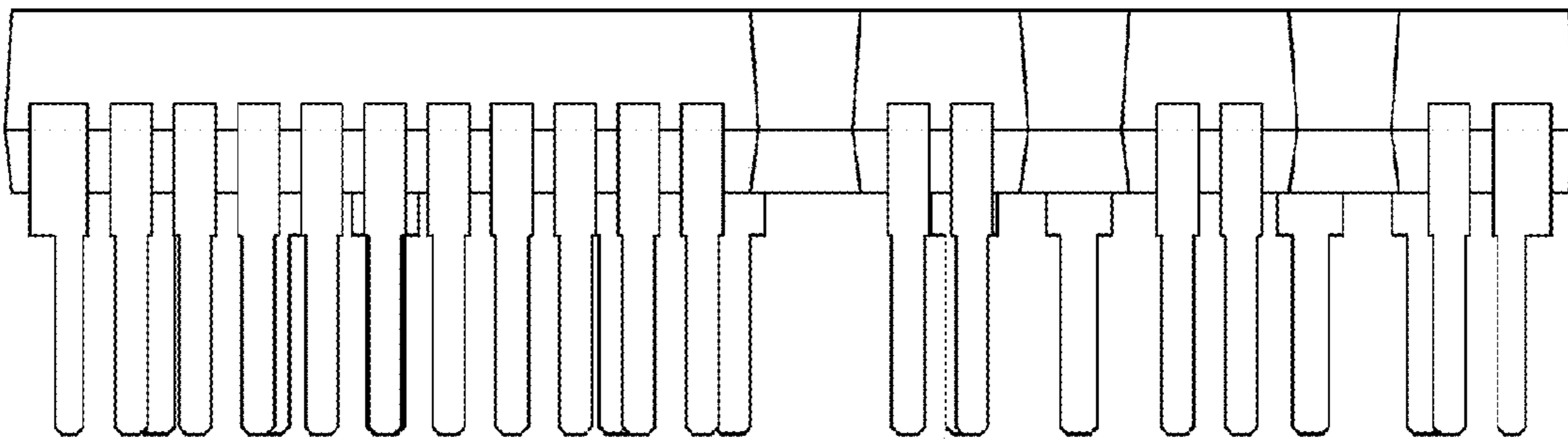


FIG. 6

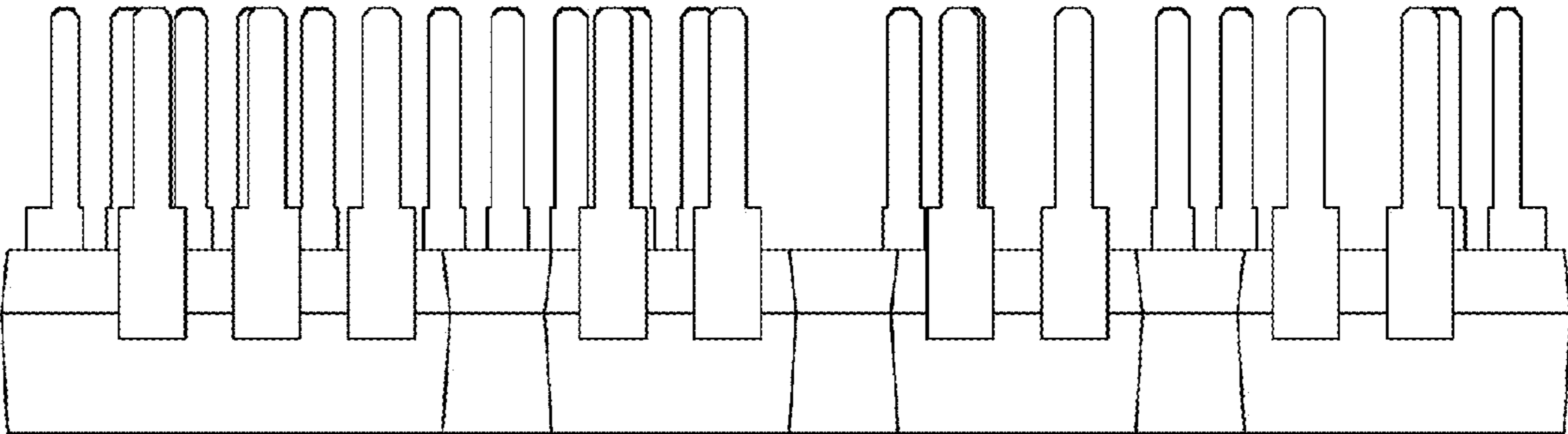


FIG. 7